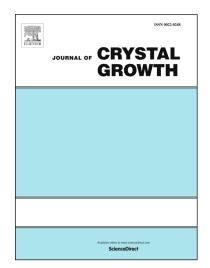
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### ACCEPTED MANUSCRIPT

# Three Dimensional Modelling of Grain Boundary Interaction and

**Evolution During Directional Solidification of Multi-crystalline Silicon** 

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